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conductivity. Such a heat-sinking material includes, e.g., Cu-W (copper-soaked tungsten) and (a jointed plate having three layers of Cu-Mo-Cu). Meanwhile, a low thermal expansion material close to ceramics in thermal expansion coefficient, such as KV and the 42-alloy, forms a peripheral extending metal portion around the bottom 16a, which supports the bottom 16a.

IN THE CLAIMS:

Amend claim 1 as follows:

1. (Amended) A high-frequency ceramic package, comprising:

a first metal plate forming a substantially rectangular shape, said first metal plate having fixing cutouts defined at both ends in a longitudinal direction thereof and further having a hollow portion formed at a central portion thereof,

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a second metal plate being fitted in said hollowed portion of said first metal plate in a relationship in which said first and second metal plates are jointed in an end to end relationship, and

a ceramic frame plate brazed to a jointed metal plate on a peripheral surface of said jointed metal plate, said jointed metal plate including said first and second metal plates,

wherein a cavity defined between said second metal plate and said ceramic frame plate accommodates a semiconductor electronic component mounting portion on a bottom of said cavity, said first metal plate being close to said ceramic frame plate in thermal expansion coefficient, said second metal plate being made from a material having an elevated degree of heat-sinking characteristics.